

MS 23 P 61

P-Channel-60-V (D-S) MOSFET

Description

These miniature surface mount MOSFETs utilize a high cell density trench process to provide low rDS(on) and to ensure minimal power loss and heat dissipation. Typical applications are DC-DC converters and power management in portable and battery-powered products such as computers, printers, PCMCIA cards, cellular and cordless telephones.

Features

- Low rDS(on) trench technology
- Low thermal impedance
- Fast switching speed
- RoHS compliant package

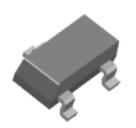
Typical Applications

- White LED boost converters
- Automotive Systems
- Industrial DC/DC Conversion Circuits

Package type: SOT-23

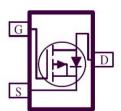
Packing & Order Information

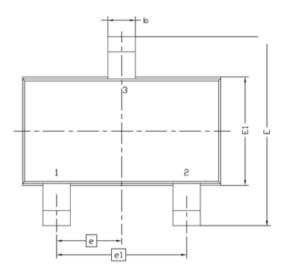
3,000/Reel

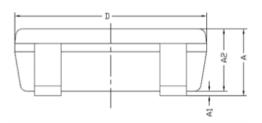


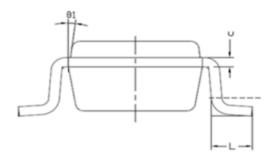
RoHS COMPLIANT

Graphic symbol









Symbol	MILLIMETERS				
Symbol	MIN	MAX			
Α	8.0	1.2			
A1	0	0.1			
A2	0.7	1.1			
b	0.3	0.5			
С	0.1	0.2			
D	2.7	3.1			
E	2.6	3			
E1	1.4	1.8			
е	0.95 BSC				
e1	1.9 BSC				
L	0.3	0.6			
θ1	7° NOM				



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MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

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Absolute Maximum Ratings (T _A =25°C unless otherwise specified)					
Symbol	Parameter	Value	Unit		
V_{DS}	Drain-Source Voltage	-60	V		
V_{GS}	Gate-Source Voltage	±20	V		
т	Continuous Drain Current ^a (T _A =25°C)	-3.4	A		
I_D	Continuous Drain Current ^a (T _A =70°C)	-2.6	A		
I_{DM}	Pulsed Drain Current ^b	-20	A		
Is	Continuous Source Current (Diode Conduction) ^a	-1.6	A		
PD	Power Dissipation ^a (T _A =25°C)	1.3	W		
	Power Dissipation ^a (T _A =70°C)	0.8	W		
T _J /T _{STG}	Operating Junction and Storage Temperature	-55 to +150	°C		

Thermal Resistance Ratings						
Symbol	Parameter	Maximum	Units			
$R_{\theta JA}$	Maximum Junction-to-Ambient ^a (t <= 10 sec)	100	°C/W			
	Maximum Junction-to-Ambient ^a (Steady-State)	166	C/W			

Notes:

- a. Surface Mounted on 1" x 1" FR4 Board.
- b. Pulse width limited by maximum junction temperature

Static						
Symbol	Parameter	Test Conditions	Min	Тур.	Max.	Units
$V_{GS(th)}$	Gate-Threshold Voltage	$V_{\mathrm{DS}} = V_{\mathrm{GS}}$, $I_{\mathrm{D}} =$ -250 μA	-1			V
I _{GSS}	Gate-Body Leakage	$V_{DS} = 0 \text{ V}$, $V_{GS} = \pm 20 \text{ V}$			±100	nA
I _{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = -48 \ V$, $V_{GS} = 0 \ V$ $V_{DS} = -48 \ V$, $V_{GS} = 0 \ V$, $T_{J} = 55 ^{\circ} C$			-1 -10	uA
I _{D(on)}	On-State Drain Current	$V_{DS} = 5 \text{ V}$, $V_{GS} = 10 \text{ V}$	-8			A
rDS (on)	Drain-Source On-Resistance	$V_{GS} = -10 \text{ V}$, $I_D = -2.7 \text{ A}$ $V_{GS} = -4.5 \text{ V}$, $I_D = -2.2 \text{ A}$			210 250	mΩ
gfs	Forward Tranconductance	$V_{DS} = -15 \text{ V}$, $I_D = -2.7 \text{ A}$		10		S
V_{SD}	Diode Forward Voltage	$I_S = -0.8 \text{ A}, V_{GS} = 0 \text{ V}$		0.83		V

Dynamic ^b							
Symbol	Parameter	Test Conditions	Min	Typ.	Max.	Units	
Q_g	Total Gate Charge			5		nC	
Q_{gs}	Gate-Source Charge	$V_{DS} = -30 \text{ V}, I_{D} = -2.7 \text{ A},$ $V_{GS} = -4.5 \text{ V}$		2.2		nC	
Q_{gd}	Gate-Drain Charge			2.3		nC	



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Dyna mic ^b							
Symbol	Parameter	Test Conditions	Min	Typ.	Max.	Units	
$t_{d(on)}$	Turn-On Delay Time	$V_{DS} = -30 \text{ V}, R_L = 11.2 \Omega,$ $V_{GEN} = -10 \text{ V}, R_{GEN} = 6 \Omega,$ $I_D = -2.7 \text{ A}$		7		ns	
$t_{\rm r}$	Rise Time			5		ns	
$t_{d(off)}$	Turn-Off Delay Time			23		ns	
tf	Fall Time			6		ns	
C _{ISS}	Input Capacitance	$\begin{split} V_{DS} = -15 \ V \ , \ V_{GS} \ = 0 \ V \ , \\ f = & 1.0 MHz \end{split} \label{eq:VDS}$		371		pF	
Coss	Output Capacitance			31		pF	
C _{RSS}	Reverse Transfer Capacitance			26		pF	

Notes:

a. Pulse test: $PW \le 300us duty cycle \le 2\%$.

b. Guaranteed by design, not subject to production testing.



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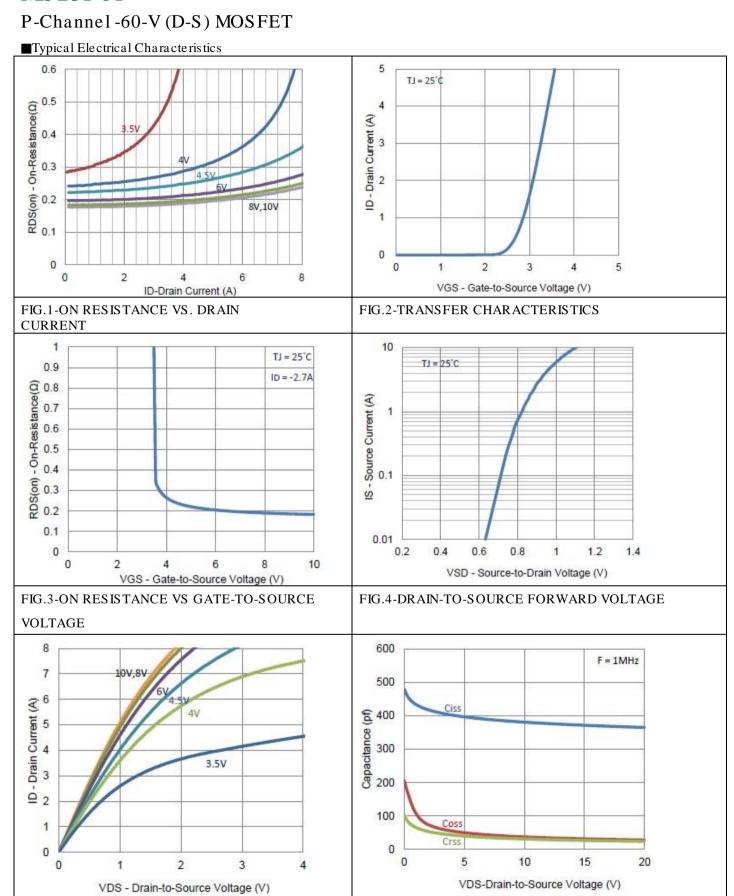


FIG.6-CAPACITANCE

FIG.5-OUTPUT CHARACTERISTICS



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Typical Electrical Characteristics

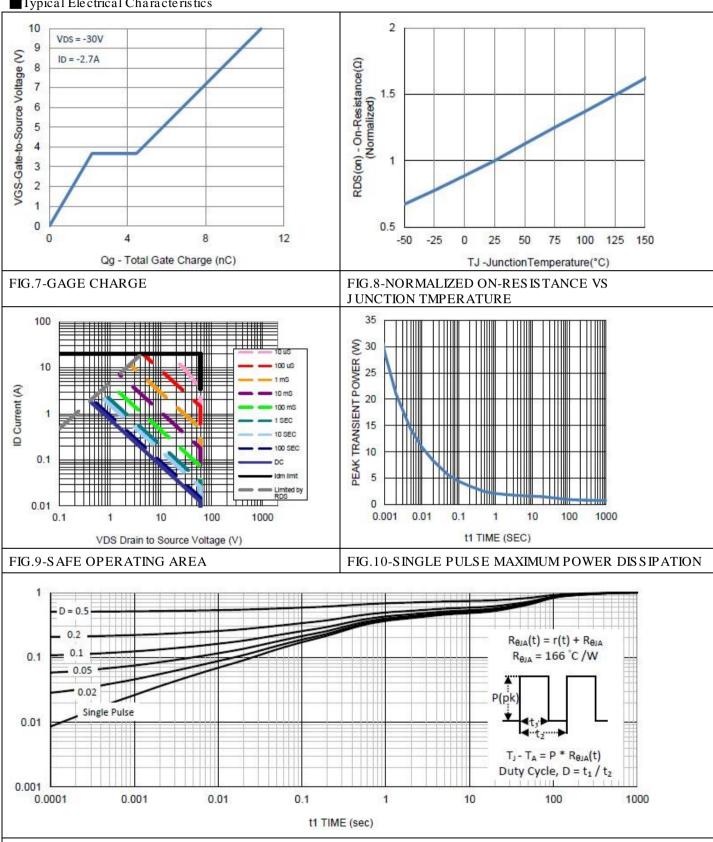


FIG.11-NORMALIZED THERMAL TRANSIENT JUNCTION TO AMBIENT



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